



# SOT762-1

plastic, leadless dual in-line compatible thermal enhanced very thin quad flat package; 14 terminals; 0.5 mm pitch; 2.5 mm x 3 mm x 0.85 mm body

4 June 2018

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	DHVQFN14
Package type industry code	DHVQFN14
Package style descriptive code	DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-241
JEITA package outline code	---
Mounting method type	S (surface mount)
Number of package outline detail graphic references	0
Issue date	5-5-2015
Manufacturer package code	SOT762

Table 1. Package summary

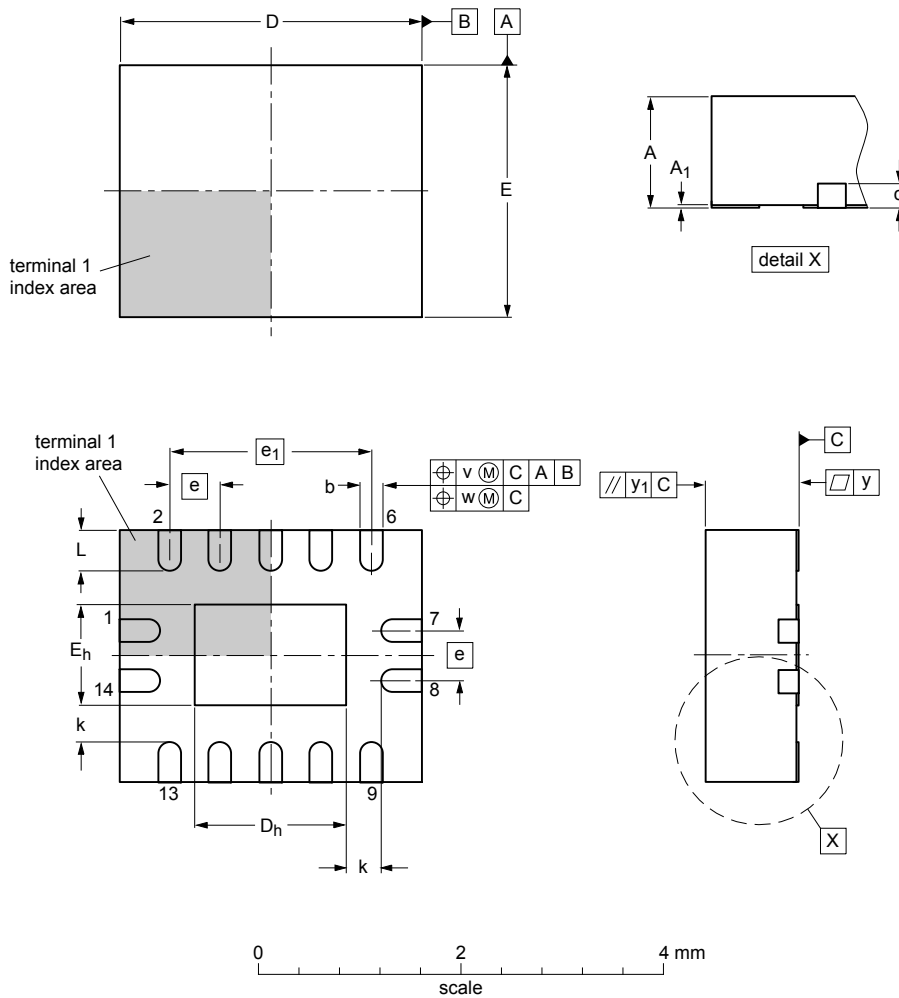
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.4	-	2.5	2.6	mm
A	seated height	-	-	-	1	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	14	-	

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## 2. Package outline

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	k	L	v	w	y	y <sub>1</sub>
max	1	0.05	0.30		3.1	1.65	2.6	1.15				0.5				
nom		0.02	0.25	0.2	3.0	1.50	2.5	1.00	0.5	2		0.4	0.1	0.05	0.05	0.1
min		0.00	0.18		2.9	1.35	2.4	0.85			0.2	0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot762-1\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT762-1		MO-241			-15-04-10- 15-05-05

Fig. 1. Package outline DHVQFN14 (SOT762-1)

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### 3. Soldering

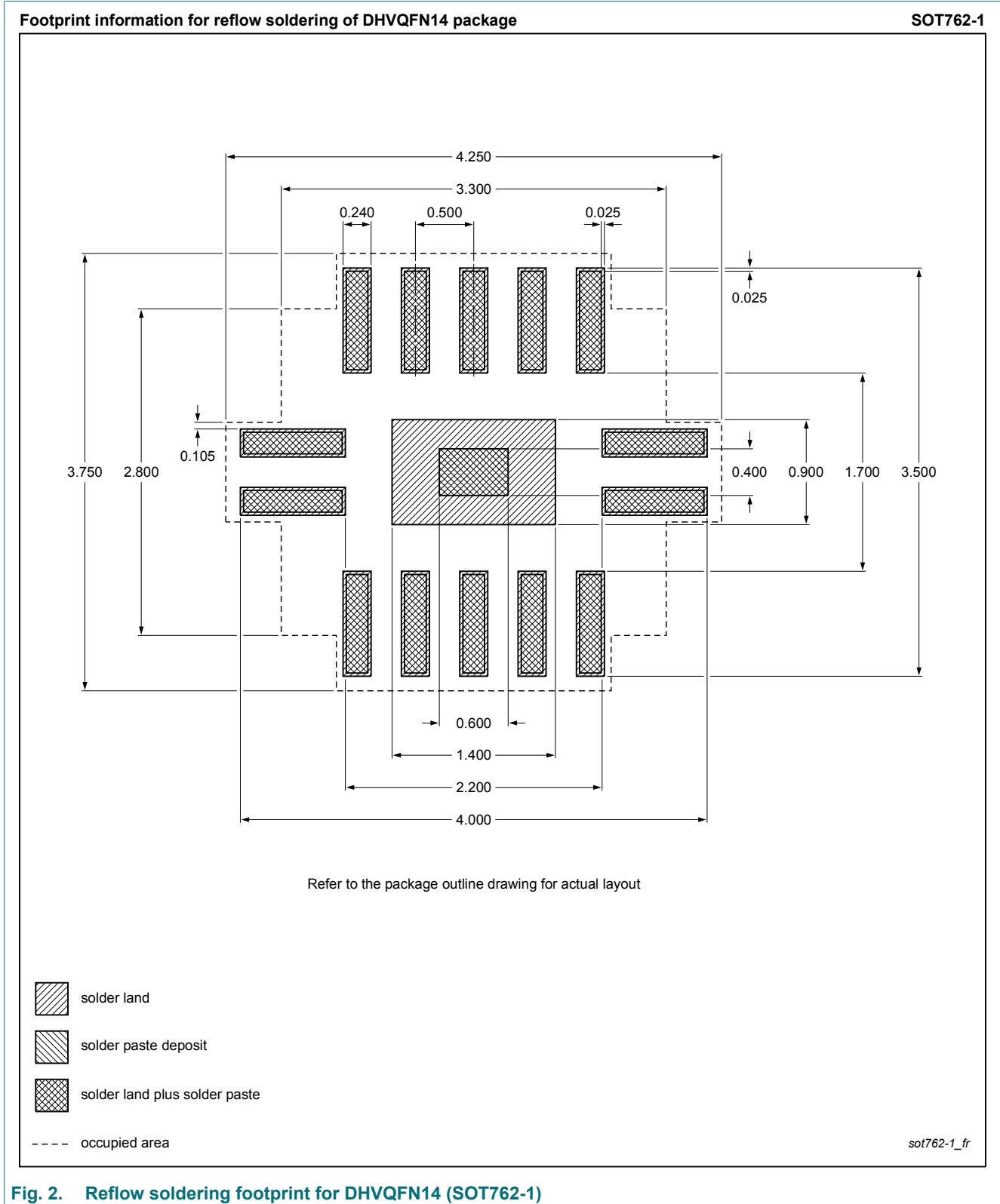


Fig. 2. Reflow soldering footprint for DHVQFN14 (SOT762-1)

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Date of release: 4 June 2018

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